Filename: PMP8500\_REVA\_bom.xls

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## PMP8500\_REVA BOM

COUNT	RefDes	Value	Description	Size	Part Number	MFR
2	C1, C2	6.8uF	CAP ALUM 6.8UF 400V 20% RADIAL	0.315 inch	UCS2G6R8MPD	Nichicon
1	C10	0.01uF	Capacitor, Ceramic, 25V, X7R, 15%	0402	STD	STD
1	C3	100uF	CAP ALUM 100UF 10V 20% RADIAL	0.315 inch	RR71A101MDN1	Nichicon
1	C4	1000uF	CAP ALUM 1000UF 10V 10mmx12.5mm	0.315 inch	STD	STD
1	C7	220pF	CAP CER 220PF 250VAC X1Y2 RAD	7.00 Dia mm	CS70-B2GA221KYNS	TDK
1	C8	0.33uF	Capacitor, Ceramic, 50V, X7R, 15%	0603	STD	STD
1	D1	SMAJ120A	Diode, Transient Voltage Suppressor, 120V	SMA	SMAJ120A	Bourns
1	D2	RH06-T	Diode, Bridge, 0.5-A, 600-V	MiniDIP	RH06-T	Diodes
1	D3	MRA4007	Diode, Rectifier, 1A, 1000V, SMA	SMA	STD	STD
1	D4	1N4148	Diode, Signal, 300-mA, 75-V, 350-mW	SOD-123	1N4148W-7-F	Diodes
1	D5	CDBC340	DIODE SCHOTTKY 3A 40V DO-214AB	SMC	CDBC340	Comchip Technology
1	F1	0.5A	FUSE SLOW 250VAC 500MA RADIAL	4x8.35 mm	RST500	BEL Fuse
1	L1	100uH	Inductor, 240mA	0.126 x 0.098 inch	ME3220-104MX	Coilcraft
1	Q1	AOD2N60	MOSFET N-CH 600V 2A DPAK		AOD2N60	Alpha & Omega Semiconductor Inc
1	R1	100	Resistor,1/4 watt, 5%	1206	STD	STD
2	R2, R10	10MEG	Resistor,1/4 watt, 5%	1206	STD	STD
1	R3	49.9	Resistor, Chip, 1/16W, 1%	0402	Std	Std
	R4	100k	Resistor, Chip, 1/16W, 1%	0402	Std	Std
1	R5	28.0k	Resistor, Chip, 1/16W, 1%	0402	Std	Std
1	R6	2.80k	Resistor, Chip, 1/16W, 1%	0402	Std	Std
1	R7	1.3	Resistor, Chip, 1/16W, 5%	0805	Std	Std
1	R8	49.9k	Resistor, Chip, 1/16W, 1%	0402	Std	Std
1	R9	2.61k	Resistor, Chip, 1/16W, 1%	0402	Std	Std
1	T2	700 uH	Transformer, ±10%	16X17 mm	G124082LF	GCI
2	TP1, TP2	5000	Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100 inch	5000	Keystone
1	TP3	5010	Test Point, Red, Thru Hole	0.125 x 0.125 inch	5010	Keystone
1	TP4	5011	Test Point, Black, Thru Hole	0.125 x 0.125 inch	5011	Keystone
1	U1	UCC28700DBV	IC, Constant Voltage, Constant Current PWM With Primary Side Regulation		UCC28700DBV	Texas Instruments

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